REMARKS

In the Office Action, claims 36-39 are rejected under 35 U.S.C. §103 as allegedly unpatentable in view of U.S. Patent Application Publication No. PCT Publication No. WO02/084631 to Hayashi ("Hayashi I") and U.S. Patent No. 5,426,342 ("Nakamura"), as evidenced by U.S. Patent No. 6,872,635 to Hayashi ("Hayashi II"), where Hayashi I is the international publication of the corresponding Hayashi II application. Also, claims 40 and 44-46 are rejected under 35 U.S.C. §103 as allegedly unpatentable over Hayashi I, Nakamura, as evidenced by Hiyashi II, and in view of U.S. Patent Application Publication No. 2003/0227253 to Seo et al. ("Seo"). The Patent Office primarily relies on the Hayashi I reference. Applicants believe that the rejections are improper as discussed in further detail below. The Commissioner is hereby authorized to charge deposit account 02-1818 for any fees which are due and owing.

Of the rejected claims, claims 36 and 41 are the sole independent claims. Claim 36 recites, at least in part, a device transfer method including: embedding other-side devices arranged on a first substrate into a pressure sensitive adhesive layer provided on a second substrate where one-side devices *are embedded in the pressure sensitive adhesive layer*; and stripping the other-side devices from the first substrate thereby holding the other-side devices in an embedded states in the pressure sensitive adhesive layer. Claim 41 recites, at least in part, a display apparatus obtained by a method comprising: *embedding one-side devices arranged on a first substrate into a pressure sensitive adhesive layer provided on a second substrate*, and stripping the one-side devices from the first substrate thereby holding the one-side devices in an embedded state in the pressure sensitive adhesive layer; *further embedding other-side devices arranged on the first substrate into the pressure sensitive adhesive layer*, and stripping the other-side devices from the first substrate thereby holding the other-side devices in an embedded state in the pressure sensitive adhesive layer, where the one-side devices are embedded in the pressure sensitive adhesive layer. Hayashi I, Hayashi II, Nakamura and Seo fail to teach or suggest all of the features of claims 36 and 41, even assuming that they are properly combinable.

Hayashi I or Hyashi II generally relates to an element transfer method, element arrangement method using the same, and an image display device. Hayashi II teaches holding devices 3a and 8 to or adhering devices onto an adhesive layer 7, as shown in Fig. 2E of Hayashi II. However, Hayashi II does not disclose *embedding* devices into the pressure sensitive

adhesive, as recited in independent claims 36 and 41. Further, Hayashi II does not disclose using pressure sensitive adhesive, as admitted on page 2 of the Office Action. An example of the presently claimed invention is illustrated in Figs. 2 and 3 of the present application, where the devices 3 are embedded into the pressure sensitive adhesive layer 5. Therefore, Hayashi II fails to teach or suggest all of the elements recited in independent claims 36 and 41.

The Office Action primarily relies on Nakamura for the alleged teaching of a method of manufacturing a fluorescent display device, using a heat sensitive and pressure sensitive adhesive layer. (See, Office Action, pg. 2). Therefore, Nakamura fails to cure the deficiencies of Hayashi II, for at least the reasons discussed above, even assuming that Nakamura is properly combinable with Hayashi II.

Based on at least these reasons, Applicants believe that the Patent Office has failed to establish a *prima facie* case of obviousness and thus respectfully request that the obviousness rejections of claims 36-46 be withdrawn.

For the foregoing reasons, Applicants respectfully submit that the present application is in condition for allowance and earnestly solicit reconsideration of same.

Respectfully submitted,

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